# Monthly LabAdviser update: 26/8 2016

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| Updated Subject | Contributor | Link to the updated pages |
| **Results of the Survey in May 2016**  Answers to comments given in the survey | **Management @danchip** | [May\_2016\_Survey](http://labadviser.danchip.dtu.dk/index.php/May_2016_Survey) |
| **Technology Research**  The aim of this page is to give an overview of the technology research going on in the cleanroom and the other laboratories facilitated by DTU Danchip. Here technology research projects will be presented | **Frederik Stöhr**  **Evgeniy Shkodin**  **Hoà Lê Thanh**  **William Tiddi**  **Matteo Todeschini**  **Bingdong Chang**  **@danchip** | [Technology\_Research](http://labadviser.danchip.dtu.dk/index.php/LabAdviser/Technology_Research) |
| **E-beam lithography – Al etch**  Al etch/strip after e-beam can be done in TMAH | **Tine Greibe @danchip** | [Lithography/EBeamLithography#Aluminum\_coating](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Lithography/EBeamLithography#Aluminum_coating) |
| **Lithography: HMDS**  Added missing HMDS priming equipment and updated QC information (contact angle measurements) for all equipment. Updated various existing pictures/texts. | **Jens Hemmingsen @danchip** | [Lithography/Pretreatment#Comparing\_HMDS\_priming](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Lithography/Pretreatment#Comparing_HMDS_priming) |
| **Lithography: Hotplates**  Hotplate equipment: Added missing equipment. Updated various existing pictures/texts. | **Jens Hemmingsen @danchip** | [Lithography/Baking](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Lithography/Baking) |
| **IBSD Ionfab**  New recipe for Si deposition with new grids | **Berit Herstrøm @danchip** | [IBSD\_Ionfab\_300/IBSD\_of\_Si](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/IBE⁄IBSD_Ionfab_300/IBSD_of_Si) |

# Equipment Manuals updated in LabManager:

As an approved user on a piece of equipment you have to make sure you have read and understood the latest version of the manual before using the equipment.

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| **Manual for IBE/IBSD Ionfab 300** |
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| **Manual for Wafer Bonder 2** |
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| **Manual for Phosphorus Drive-in furnace (A3)** |
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| **Manual for Phosphorus Predep furnace (A4)** |
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| **Manual for RTP Jipelec** |
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| **Manual for furnace computer- A, B, C, D and E-stack** |
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| **Manual for Boron Drive-in + Pre-dep Furnace (A1)** |
| **Manual for AFM Icon-PT** |
| **Regler for arbejde med kemi på Danchip** |
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| **Rules for working with Chemistry at Danchip** |

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